# 5-146852-1 ✓ ACTIVE

## AMPMODU | AMPMODU Headers

TE Internal #: 5-146852-1

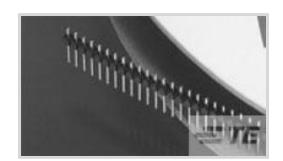
PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal,

AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 10

Number of Rows: 1

## **Features**

## **Product Type Features**

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

## **Configuration Features**

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	10
Number of Rows	1
Board-to-Board Configuration	Parallel

## **Body Features**

Connector Profile	Standard
Primary Product Color	Black

#### **Contact Features**

Mating Square Post Dimension	.64 mm[.025 in]
	100 – 200 μin
Contact Shape & Form	Square



PCB Contact Lemination Area Plating Material Contact Base Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Inlickness 2,54 – 5,08 µm[100 – 200 µin] Contact Type Pin Contact Current Rating (Max) 3 A  Termination Features  Square Lemination Post & Tail Dimension 6,44 mm[,025 in] Termination Post & Tail Length 2,92 mm[,115 in] Termination Method to PCB Through Hole - Solder  Mechanical Attachment  Mating Alignment Without PCB Mount Retention PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features  Centerline (Pitch) 4,54 mm[,1 in] Housing Material Thermoplastic  Dimensions  PCB Thickness (Recommended) 1,6 mm[,063 in]  Usage Conditions  Housing Temperature Rating Departing Temperature Rating Operating Temperature Raring Solder Process Leature Board Standoff Circuit Application Solder Process Leature Gircuit Application Signal Industry Standards	Contact Underplating Material	Nickel
Contact Base Material Copper Alloy  Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin]  Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin]  Contact Lype Pin  Contact Current Rating (Max) 3.A  Termination Features  Square Termination Post & Tail Dimension .64 mm[.025 in]  Termination Post & Tail Length 2.92 mm[.115 in]  Termination Method to PCB Through Hole - Solder  Mechanical Attachment  Mating Alignment Without  PCB Mount Retention Without  PCB Mount Alignment Without  Connector Mounting Type Board Mount  Housing Features  Centerline (Pitch) 2.54 mm[.1 in]  Housing Material Thermoplastic  Dimensions  PCB Thickness (Recommended) 1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating High  Operating Temperature Range .65 – 105 °C[.85 – 221 °F]  Operation/Application  Solder Process Feature Board Standoff  Circuit Application		
Contact Mating Area Plating Material Tin  Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin]  Contact Type Pin  Contact Current Rating (Max) 3.A  Termination Features  Square Termination Post & Tail Dimension .64 mm[.025 in]  Termination Post & Tail Length 2.92 mm[.115 in]  Termination Method to PCB Through Hole - Solder  Mechanical Attachment  Mating Alignment Without  PCB Mount Retention Without  PCB Mount Alignment Without  Connector Mounting Type Board Mount  Housing Features  Centerline (Pitch) 2.54 mm[.1 in]  Housing Material Thermoplastic  Dimensions  PCB Thickness (Recommended) 1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating High  Operating Temperature Rating High  Operating Temperature Range -65 – 105 "CJ-85 – 221 "FJ  Operation/Application  Solder Process Feature Board Standoff  Circuit Application Signal		Copper Alloy
Contact Type Pin Contact Current Rating (Max) 3 A  Termination Features  Square Termination Post & Tail Dimension .64 mml,025 in  Termination Post & Tail Length 2.92 mm[.115 in] Termination Method to PCB Through Hole Solder  Mechanical Attachment  Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount  Housing Features  Centerline (Pitch) 2.54 mml,1 in  Housing Material Thermoplastic  Dimensions  PCB Thickness (Recommended) 1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating High Operating Temperature Range -65 – 105 °C[.85 – 221 °F]  Operation/Application  Solder Process Feature Board Standolf Circuit Application Signal	Contact Mating Area Plating Material	
Contact Current Rating (Max)  Termination Features  Square Termination Post & Tail Dimension .64 mm [.025 in]  Termination Post & Tail Length .2.92 mm [.115 in]  Termination Method to PCB .Through Hole - Solder  Mechanical Attachment  Mating Alignment .Without  PCB Mount Retention .Without  PCB Mount Alignment .Without  Connector Mounting Type .Board Mount  Housing Features  Centerline (Pitch) .2.54 mm [.1 in]  Thermoplastic  Dimensions  PCB Thickness (Recommended) .1.6 mm [.063 in]  Usage Conditions  Housing Temperature Rating .High  Operating Temperature Range65 - 105 °C[-85 - 221 °F]  Operation/Application  Solder Process Feature .Board Standoff  Circuit Application .Signal	Contact Mating Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Termination Features  Square Termination Post & Tail Dimension .64 mm[.025 in]  Termination Post & Tail Length .2.92 mm[.115 in]  Termination Method to PCB .Through Hole - Solder  Mechanical Attachment  Mating Alignment .Without  PCB Mount Retention .Without  PCB Mount Alignment .Without  Connector Mounting Type .Board Mount  Housing Features  Centerline (Pitch) .2.54 mm[.1 in]  Housing Material .Thermoplastic  Dimensions  PCB Thickness (Recommended) .1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating .High  Operation/Application  Solder Process Feature .Board Standoff  Circuit Application .Signal	Contact Type	Pin
Square Termination Post & Tail Dimension  Termination Post & Tail Length  2.92 mm[.115 in]  Termination Method to PCB  Through Hole Solder  Mechanical Attachment  Mating Alignment  PCB Mount Retention  PCB Mount Alignment  Without  Connector Mounting Type  Board Mount  Housing Features  Centerline (Pitch)  Ausing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Contact Current Rating (Max)	3 A
Termination Post & Tail Length  Termination Method to PCB  Through Hole - Solder  Mechanical Attachment  Mating Alignment  Without  PCB Mount Retention  PCB Mount Alignment  Without  Connector Mounting Type  Board Mount  Housing Features  Centerline (Pitch)  2.54 mm[.1 in]  Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  High  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application	Termination Features	
Termination Method to PCB  Mechanical Attachment  Mating Alignment  Mount Retention  PCB Mount Retention  Without  Connector Mounting Type  Board Mount  Housing Features  Centerline (Pitch)  Losing Material  Dimensions  PCB Thickness (Recommended)  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application	Square Termination Post & Tail Dimension	.64 mm[.025 in]
Mechanical Attachment  Mating Alignment  PCB Mount Retention  Without  PCB Mount Alignment  Without  Connector Mounting Type  Board Mount  Housing Features  Centerline (Pitch)  Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Termination Post & Tail Length	2.92 mm[.115 in]
Mating Alignment  PCB Mount Retention  Without  PCB Mount Alignment  Without  Connector Mounting Type  Board Mount  Housing Features  Centerline (Pitch)  2.54 mm[.1 in]  Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Termination Method to PCB	Through Hole - Solder
PCB Mount Retention Without  PCB Mount Alignment Without  Connector Mounting Type Board Mount  Housing Features  Centerline (Pitch) 2.54 mm[.1 in]  Housing Material Thermoplastic  Dimensions  PCB Thickness (Recommended) 1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating High  Operating Temperature Range -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature Board Standoff  Circuit Application Signal	Mechanical Attachment	
PCB Mount Alignment  Connector Mounting Type  Board Mount  Housing Features  Centerline (Pitch)  Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  High  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Mating Alignment	Without
Connector Mounting Type  Housing Features  Centerline (Pitch)  Housing Material  Dimensions  PCB Thickness (Recommended)  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Mount  1.6 mm[.0 in]  1.6 mm[.063 in]  High  Operation CF-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application	PCB Mount Retention	Without
Housing Features  Centerline (Pitch)  Lousing Material  Centerline (Pitch)  Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	PCB Mount Alignment	Without
Centerline (Pitch)  Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  2.54 mm[.1 in]  Thermoplastic  2.54 mm[.1 in]  Thermoplastic  PM mm[.063 in]  1.6 mm[.063 in]  -65 – 105 °C[-85 – 221 °F]  Signal	Connector Mounting Type	Board Mount
Housing Material  Thermoplastic  Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Housing Features	
Dimensions  PCB Thickness (Recommended)  1.6 mm[.063 in]  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Centerline (Pitch)	2.54 mm[.1 in]
PCB Thickness (Recommended)  Usage Conditions  Housing Temperature Rating  Operating Temperature Range  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  1.6 mm[.063 in]  High  October Process Feature Range  Board Standoff  Signal	Housing Material	Thermoplastic
Usage Conditions  Housing Temperature Rating  Operating Temperature Range  -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Dimensions	
Housing Temperature Rating  Operating Temperature Range  -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	PCB Thickness (Recommended)	1.6 mm[.063 in]
Operating Temperature Range  -65 – 105 °C[-85 – 221 °F]  Operation/Application  Solder Process Feature  Board Standoff  Circuit Application  Signal	Usage Conditions	
Operation/Application         Solder Process Feature       Board Standoff         Circuit Application       Signal	Housing Temperature Rating	High
Solder Process Feature  Board Standoff  Circuit Application  Signal	Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Circuit Application Signal	Operation/Application	
	Solder Process Feature	Board Standoff
Industry Standards	Circuit Application	Signal
	Industry Standards	
Compatible With Approved Standards Products CSA LR7189, UL E28476	Compatible With Approved Standards Products	CSA LR7189, UL E28476
UL Flammability Rating  UL 94V-0		UL 94V-0
Packaging Features	Packaging Features	
Packaging Quantity 25000	Packaging Quantity	25000



Packaging Method	Reel	

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**



Also in the Series | AMPMODU Headers





Connector Caps & Covers(1)



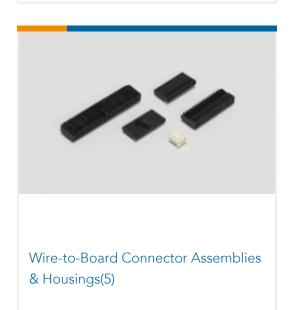
Connector Contacts(64)



Connector Hardware(2)



PCB Headers & Receptacles(3202)



# Customers Also Bought



TE Part #3-641536-2 02P MTA100 CONN ASSY 26AWG

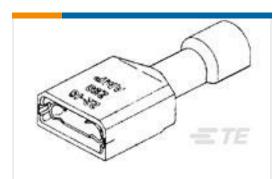


TE Part #6-173977-3
CT CONN MT REC ASSY 3P BLACK



TE Part #5414373-1 JACK,PCB,50 OHM,BNC

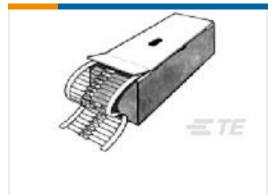




TE Part #2-520182-2 ULTRAFAST 187 ASSY REC 22-18 TPBR LP



TE Part #1-1437597-7
2SWK131AL101=NON UL KEYLOCK
SW



TE Part #1-2176083-1 EP 5W (S) 470R 5%





TE Part #1625889-6 2W SM M/OX 2% 6R8 REELED



TE Part #5677934005 RNF-3000-9/3-X-SP

# **Documents**

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



**Product Drawings** 

B/A REELED SRST HDR ASSY, SN

English

Datasheets & Catalog Pages

AMPMODU\_INTERCONNECTION\_SYSTEM\_SECTION5

English

1-1773720-9\_AMPMODU\_MOD\_IV\_V\_QRG

English